Preferred Device

Sensitive Gate Silicon Controlled Rectifiers

Reverse Blocking Thyristors

Annular PNPN devices designed for high volume consumer applications such as relay and lamp drivers, small motor controls, gate drivers for larger thyristors, and sensing and detection circuits. Supplied in an inexpensive plastic TO-92/TO-226AA package which is readily adaptable for use in automatic insertion equipment.

Features

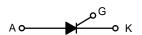
- Sensitive Gate Trigger Current 200 μA Maximum
- Low Reverse and Forward Blocking Current $50 \mu A$ Maximum, $T_C = 110^{\circ} C$
- Low Holding Current 5 mA Maximum
- Passivated Surface for Reliability and Uniformity
- Device Marking: Device Type, e.g., 2N5060, Date Code
- Pb-Free Packages are Available*



ON Semiconductor®

http://onsemi.com

SILICON CONTROLLED RECTIFIERS 0.8 A RMS, 30 – 200 V







50xx Specific Device Code

Y = Year WW = Work Week

PIN ASSIGNMENT			
1 Cathode			
2	Gate		
3	Anode		

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Repetitive Off–State Voltage (Note 1) $ (T_J = -40 \text{ to } 110^{\circ}\text{C}, \text{ Sine Wave}, \\ 50 \text{ to } 60 \text{ Hz}, \text{ Gate Open}) & 2N5060 \\ & 2N5061 \\ & 2N5062 \\ & 2N5064 $	V _{DRM,} V _{RRM}	30 60 100 200	V
On-State Current RMS (180° Conduction Angles; T _C = 80°C)	I _{T(RMS)}	0.8	А
*Average On-State Current (180° Conduction Angles) (T _C = 67°C) (T _C = 102°C)	I _{T(AV)}	0.51 0.255	A
*Peak Non-repetitive Surge Current, $T_A = 25^{\circ}C$ (1/2 cycle, Sine Wave, 60 Hz)	I _{TSM}	10	А
Circuit Fusing Considerations (t = 8.3 ms)	I ² t	0.4	A ² s
*Average On-State Current (180° Conduction Angles) (T _C = 67°C) (T _C = 102°C)	I _{T(AV)}	0.51 0.255	A
*Forward Peak Gate Power (Pulse Width $\leq 1.0 \mu sec; T_A = 25^{\circ}C$)	P_{GM}	0.1	W
*Forward Average Gate Power (T _A = 25°C, t = 8.3 ms)	$P_{G(AV)}$	0.01	W
*Forward Peak Gate Current (Pulse Width ≤ 1.0 μsec; T _A = 25°C)	I _{GM}	1.0	Α
*Reverse Peak Gate Voltage (Pulse Width ≤ 1.0 µsec; T _A = 25°C)	V_{RGM}	5.0	V
*Operating Junction Temperature Range	TJ	-40 to +110	°C
*Storage Temperature Range	T _{stg}	-40 to +150	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
*Thermal Resistance, Junction-to-Case (Note 2)	$R_{ heta JC}$	75	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{ heta JA}$	200	°C/W
Lead Solder Temperature (Lead Length ≥ 1/16" from case, 10 s Max)	_	+230	°C

^{2.} This measurement is made with the case mounted "flat side down" on a heatsink and held in position by means of a metal clamp over the curved surface.

V_{DRM} and V_{RRM} for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate
voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current
source such that the voltage ratings of the devices are exceeded.

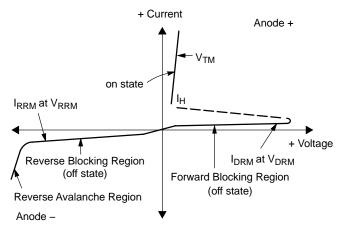
^{*}Indicates JEDEC Registered Data.

ELECTRICAL CHARACTERISTICS ($T_C = 25^{\circ}C$ unless otherwise noted)

Characteristic		Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS						
*Peak Repetitive Forward or Reverse B (V _{AK} = Rated V _{DRM} or V _{RRM})	locking Current (Note 3) $T_C = 25^{\circ}C$ $T_C = 110^{\circ}C$	I _{DRM} , I _{RRM}	_ _	_ _	10 50	μ Α μ Α
ON CHARACTERISTICS						
*Peak Forward On-State Voltage (Note (I _{TM} = 1.2 A peak @ T _A = 25°C)	4)	V _{TM}	-	_	1.7	V
Gate Trigger Current (Continuous DC) (* $(V_{AK} = 7.0 \text{ Vdc}, R_L = 100 \Omega)$	Note 5) $T_{C} = 25^{\circ}C$ $T_{C} = -40^{\circ}C$	I _{GT}	- -	- -	200 350	μΑ
Gate Trigger Voltage (Continuous DC) ($^*(V_{AK} = 7.0 \text{ Vdc}, R_L = 100 \Omega)$	Note 5) $T_{C} = 25^{\circ}C$ $T_{C} = -40^{\circ}C$	V _{GT}	- -	- -	0.8 1.2	٧
*Gate Non–Trigger Voltage $(V_{AK} = Rated V_{DRM}, R_L = 100 \Omega) T_C = 0$	- 110°C	V_{GD}	0.1	_	_	٧
Holding Current (Note 5) *(V _{AK} = 7.0 Vdc, initiating current = 20	$T_C = 25^{\circ}C$ O mA) $T_C = -40^{\circ}C$	Iн	- -	- -	5.0 10	mA
Turn-On Time Delay Time Rise Time $(I_{GT} = 1.0 \text{ mA}, V_D = \text{Rated } V_{DRM}, Forward Current = 1.0 A, di/dt = 6.0 A}$	Vµs	t _d t _r	_ _	3.0 0.2	- -	μs
Turn-Off Time (Forward Current = 1.0 A pulse, Pulse Width = 50 μ s, 0.1% Duty Cycle, di/dt = 6.0 A/ μ s, dv/dt = 20 V/ μ s, I _{GT} = 1 mA)	2N5060, 2N5061 2N5062, 2N5064	tq	_ _ _	10 30	- -	μs
DYNAMIC CHARACTERISTICS						
Critical Rate of Rise of Off–State Voltage (Rated V _{DRM} , Exponential)	3	dv/dt	-	30	_	V/μs

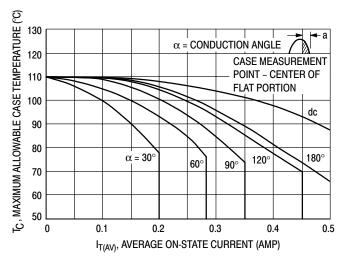
Voltage Current Characteristic of SCR

Symbol	Parameter
V_{DRM}	Peak Repetitive Off State Forward Voltage
I _{DRM}	Peak Forward Blocking Current
V_{RRM}	Peak Repetitive Off State Reverse Voltage
I _{RRM}	Peak Reverse Blocking Current
V_{TM}	Peak on State Voltage
I _H	Holding Current



^{3.} R_{GK} = 1000 Ω is included in measurement. 4. Forward current applied for 1 ms maximum duration, duty cycle \leq 1%. 5. R_{GK} current is not included in measurement. *Indicates JEDEC Registered Data.

CURRENT DERATING

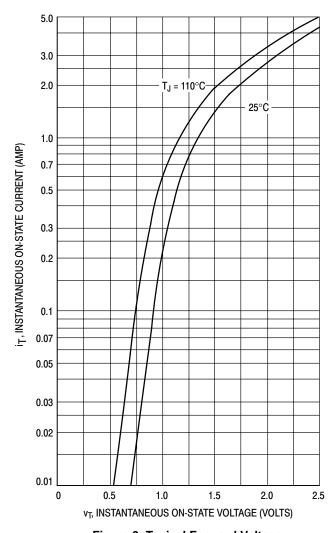


130 T_A , MAXIMUM ALLOWABLE AMBIENT α = CONDUCTION ANGLE 110 TEMPERATURE (°C) TYPICAL PRINTED CIRCUIT BOARD 90 MOUNTING 70 dc 50 180° $\alpha = 30^{\circ}$ 60 30 0 0.1 0.2 0.3 0.4 $I_{T(AV)}$, AVERAGE ON-STATE CURRENT (AMP)

Figure 1. Maximum Case Temperature

Figure 2. Maximum Ambient Temperature

CURRENT DERATING





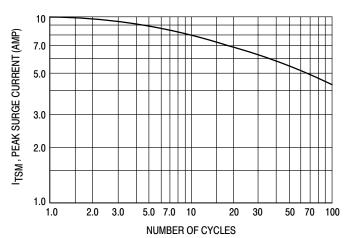


Figure 4. Maximum Non-Repetitive Surge Current

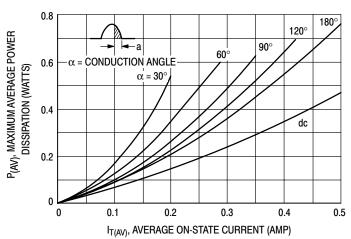


Figure 5. Power Dissipation

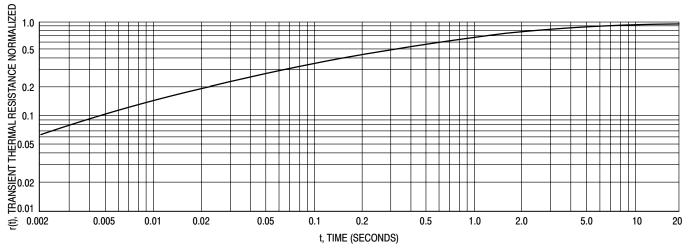
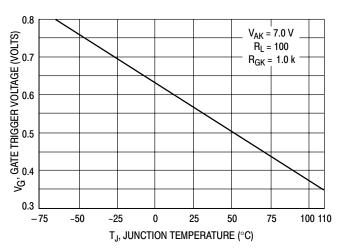


Figure 6. Thermal Response

TYPICAL CHARACTERISTICS



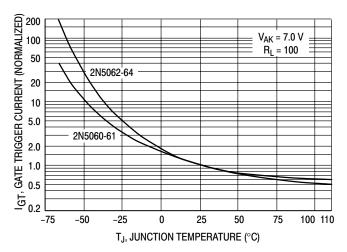


Figure 7. Typical Gate Trigger Voltage

Figure 8. Typical Gate Trigger Current

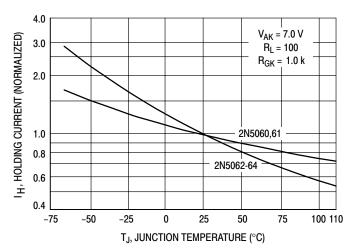


Figure 9. Typical Holding Current

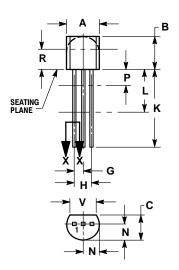
ORDERING INFORMATION

Device	Package	Shipping [†]
2N5060	TO-92	5,000 Units / Box
2N5060RLRA	TO-92	2,000 / Tape & Reel
2N5060RLRAG	TO-92 (Pb-Free)	2,000 / Tape & Reel
2N5060RLRM	TO-92	2,000 / Ammo Pack
2N5061	TO-92	5,000 Units / Box
2N5061G	TO-92 (Pb-Free)	5,000 Units / Box
2N5061RLRA	TO-92	2,000 / Tape & Reel
2N5061RLRAG	TO-92 (Pb-Free)	2,000 / Tape & Reel
2N5061RLRM	TO-92	2,000 / Ammo Pack
2N5062	TO-92	5,000 Units / Box
2N5062G	TO-92 (Pb-Free)	5,000 Units / Box
2N5062RLRA	TO-92	2,000 / Tape & Reel
2N5062RLRAG	TO-92 (Pb-Free)	2,000 / Tape & Reel
2N5064	TO-92	5,000 Units / Box
2N5064RLRA	TO-92	2,000 / Tape & Reel
2N5064RLRM	TO-92	2,000 / Ammo Pack
2N5064RLRMG	TO-92 (Pb-Free)	2,000 / Ammo Pack
2N5060RL1	TO-92	2,000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

TO-92 **TO-226AA** CASE 29-11 **ISSUE AL**





- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
 4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.175	0.205	4.45	5.20
В	0.170	0.210	4.32	5.33
С	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
Н	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500		12.70	
L	0.250		6.35	
N	0.080	0.105	2.04	2.66
Р		0.100		2.54
R	0.115		2.93	
٧	0.135		3.43	

STYLE 10: PIN 1. CATHODE 2. GATE 3. ANODE

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability, arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 61312, Phoenix, Arizona 85082–1312 USA Phone: 480–829–7710 or 800–344–3860 Toll Free USA/Canada Fax: 480–829–7709 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800–282–9855 Toll Free LISA/Canada

Japan: ON Semiconductor, Japan Customer Focus Center 2–9–1 Kamimeguro, Meguro–ku, Tokyo, Japan 153–0051 Phone: 81–3–5773–3850

ON Semiconductor Website: http://onsemi.com

Order Literature: http://www.onsemi.com/litorder

For additional information, please contact your local Sales Representative.

2N5060/D